Wednesday, October 6, 2021

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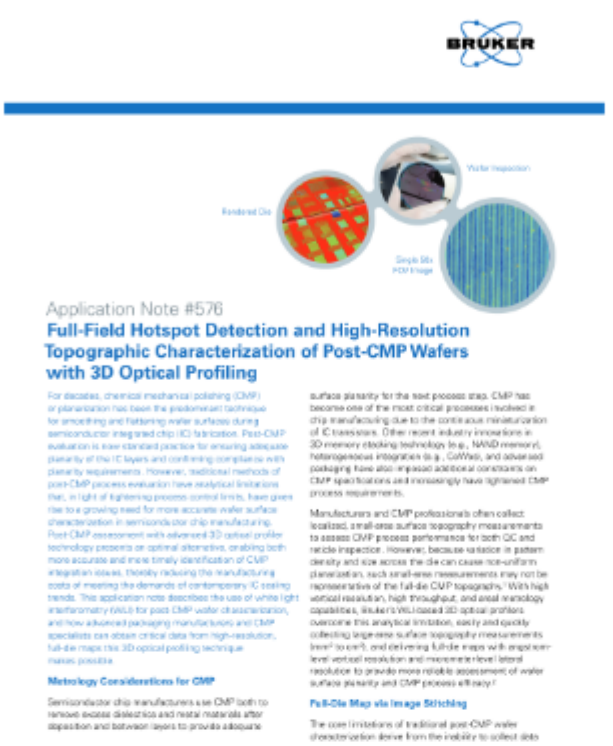

Full-Field Hotspot Detection and High-Resolution Topographic Characterization of Post-CMP Wafers with 3D Optical Profiling

Traditional methods of post-CMP process evaluation have analytical limitations that, in light of tightening process control limits, do not meet the growing need for more accurate wafer surface characterization in semiconductor chip manufacturing. This application note describes how white light interferometry (WLI) enables advanced packaging manufacturers and CMP specialists to obtain critical data from the high-resolution, full-die maps this 3D optical profiling technique makes possible.

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